

# LMR14203

***LMR14203 SIMPLE SWITCHER® 42Vin, 0.3A Step-Down Voltage Regulator in  
SOT-23***



Literature Number: SNVS732A

## LMR14203

# SIMPLE SWITCHER® 42Vin, 0.3A Step-Down Voltage Regulator in SOT-23

### Features

- Input voltage range of 4.5V to 42V
- Output voltage range of 0.765V to 34V
- Output current up to 0.3A
- 1.25 MHz switching frequency
- Low shutdown  $I_q$ , 16  $\mu$ A typical
- Short circuit protected
- Internally compensated
- Soft-start function
- Thin SOT23-6 package (2.97 x 1.65 x 1mm)
- Fully enabled for WEBENCH® Power Designer

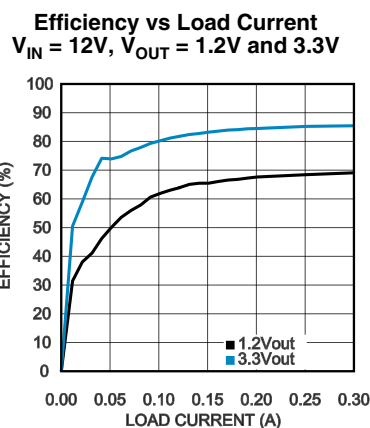
### Applications

- Point-of-Load Conversions from 5V, 12V, and 24V Rails
- Space Constrained Applications
- Battery Powered Equipment
- Industrial Distributed Power Applications
- Power Meters
- Portable Hand-Held Instruments

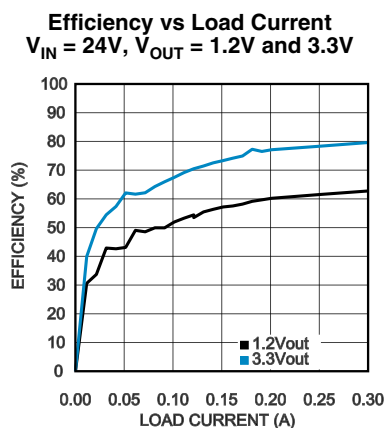
### Performance Benefits

- Tight accuracy for powering digital ICs
- Extremely easy to use
- Tiny overall solution reduces system cost

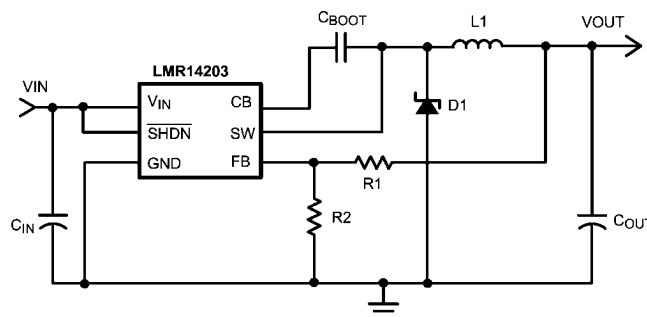
### System Performance



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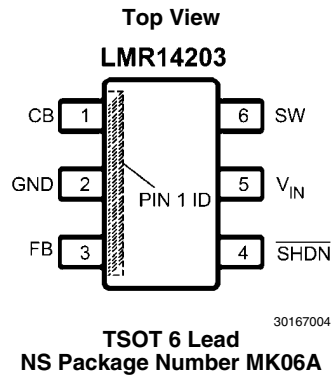


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## Connection Diagram



## Ordering Information

Order Number	Spec.	Package Type	NSC Package Drawing	Top Mark	Supplied As
LMR14203XMKE	NOPB	TSOT-6	MK06A	SJ3B	250 Units, Tape and Reel
LMR14203XMK					1000 Units, Tape and Reel
LMR14203XMKX					3000 Units, Tape and Reel

## Pin Descriptions

Pin	Name	Function
1	CB	SW FET gate bias voltage. Connect $C_{BOOT}$ cap between CB and SW.
2	GND	Ground connection.
3	FB	Feedback pin: Set feedback voltage divider ratio with $V_{OUT} = V_{FB} (1 + (R1/R2))$ . Resistors should be in the 100-10K range to avoid input bias errors.
4	$\overline{SHDN}$	Logic level shutdown input. Pull to GND to disable the device and pull high to enable the device. If this function is not used tie to $V_{IN}$ or leave open.
5	$V_{IN}$	Power input voltage pin: 4.5V to 42V normal operating range.
6	SW	Power FET output: Connect to inductor, diode, and $C_{BOOT}$ cap.

## Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

$V_{IN}$	-0.3V to +45V
$\overline{SHDN}$	-0.3V to ( $V_{IN}+0.3V$ ) $\overline{SHDN}=V_{IN}$ at 45V max
SW Voltage	-0.3V to +45V
CB Voltage above SW Voltage	7V
FB Voltage	-0.3V to +5V
Maximum Junction Temperature	150°C
Power Dissipation (Note 2)	Internally Limited

For soldering specifications: see product folder at [www.national.com](http://www.national.com) and [www.national.com/ms/MS/MS-SOLDERING.pdf](http://www.national.com/ms/MS/MS-SOLDERING.pdf)

ESD Susceptibility (Note 3)

Human Body Model

1.5 kV

## Operating Conditions

Operating Junction Temperature Range (Note 4)	-40°C to +125°C
Storage Temperature	-65°C to +150°C
Input Voltage $V_{IN}$	4.5V to 42V
SW Voltage	Up to 42V

## Electrical Characteristics

Specifications in standard type face are for  $T_J = 25^\circ\text{C}$  and those with **boldface type** apply over the full **Operating Temperature Range** ( $T_J = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ ). Minimum and Maximum limits are guaranteed through test, design, or statistical correlation. Typical values represent the most likely parametric norm at  $T_J = +25^\circ\text{C}$ , and are provided for reference purposes only. Unless otherwise stated the following conditions apply:  $V_{IN} = 12V$ .

Symbol	Parameter	Conditions	Min (Note 4)	Typ (Note 5)	Max (Note 4)	Units
$I_Q$	Quiescent current	$\overline{SHDN} = 0V$		16	<b>40</b>	$\mu A$
		Device On, Not Switching		1.30	<b>1.75</b>	mA
		Device On, No Load		1.35	<b>1.85</b>	
$R_{DS(ON)}$	Switch ON resistance	(Note 6)		0.9	<b>1.6</b>	$\Omega$
$I_{LSW}$	Switch leakage current	$V_{IN} = 42V$		0.0	0.5	$\mu A$
$I_{CL}$	Switch current limit	(Note 7)		525		mA
$I_{FB}$	Feedback pin bias current	(Note 8)		0.1	1.0	$\mu A$
$V_{FB}$	FB Pin reference voltage		<b>0.747</b>	0.765	<b>0.782</b>	V
$t_{MIN}$	Minimum ON time			100		ns
$f_{SW}$	Switching frequency	$V_{FB} = 0.5V$	<b>0.95</b>	1.25	<b>1.50</b>	MHz
		$V_{FB} = 0V$		0.35		
$D_{MAX}$	Maximum duty cycle		<b>81</b>	87		%
$V_{UVP}$	Undervoltage lockout thresholds	On threshold	<b>4.4</b>	3.7		V
		Off threshold		3.5	<b>3.25</b>	
$V_{\overline{SHDN}}$	Shutdown threshold	Device on	<b>2.3</b>	1.0		V
		Device off		0.9	<b>0.3</b>	
$I_{\overline{SHDN}}$	Shutdown pin input bias current	$V_{\overline{SHDN}} = 2.3V$ (Note 8)		0.05	<b>1.5</b>	$\mu A$
		$V_{\overline{SHDN}} = 0V$		0.02	<b>1.5</b>	

### THERMAL SPECIFICATIONS

$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance, TSOT-6L Package	(Note 9)		121		$^\circ\text{C/W}$
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**Note 1:** Absolute maximum ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions for which the device is intended to be functional, but device parameter specifications may not be guaranteed. For guaranteed specifications and test conditions, see the Electrical Characteristics.

**Note 2:** The maximum allowable power dissipation is a function of the maximum junction temperature,  $T_{J(MAX)}$ , the junction-to-ambient thermal resistance,  $\theta_{JA}$ , and the ambient temperature,  $T_A$ . The maximum allowable power dissipation at any ambient temperature is calculated using:  $P_D (MAX) = (T_{J(MAX)} - T_A) / \theta_{JA}$ . Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage. Thermal shutdown engages at  $T_J=175^\circ\text{C}$  (typ.) and disengages at  $T_J=155^\circ\text{C}$  (typ).

**Note 3:** Human Body Model, applicable std. JESD22-A114-C.

**Note 4:** All limits guaranteed at room temperature (standard typeface) and at temperature extremes (bold typeface). All room temperature limits are 100% production tested. All limits at temperature extremes are guaranteed via correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).

**Note 5:** Typical numbers are at  $25^\circ\text{C}$  and represent the most likely norm.

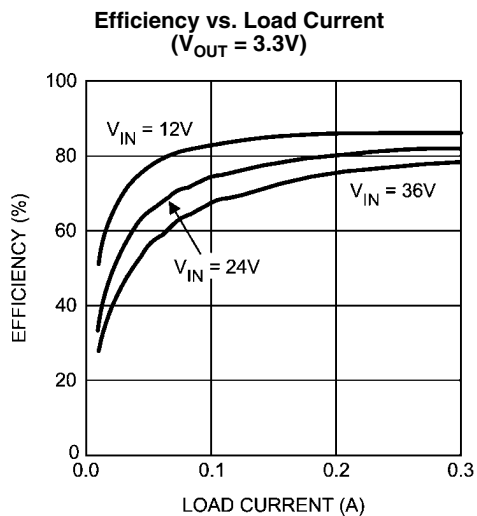
**Note 6:** Includes the bond wires,  $R_{DS(ON)}$  from  $V_{IN}$  pin to SW pin.

**Note 7:** Current limit at 0% duty cycle.

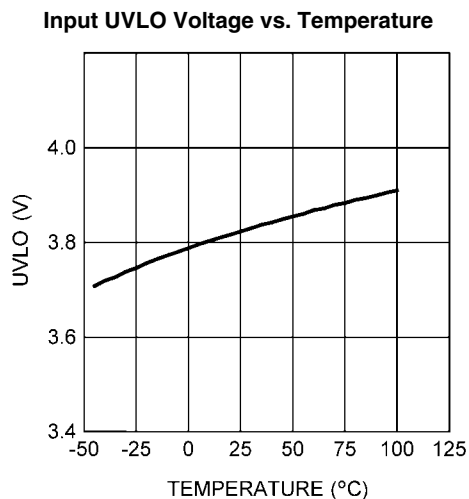
**Note 8:** Bias currents flow into pin.

**Note 9:** All numbers apply for packages soldered directly onto a 3" x 3" PC board with 2 oz. copper on 4 layers in still air in accordance to JEDEC standards. Thermal resistance varies greatly with layout, copper thickness, number of layers in PCB, power distribution, number of thermal vias, board size, ambient temperature, and air flow.

## Typical Performance Characteristics

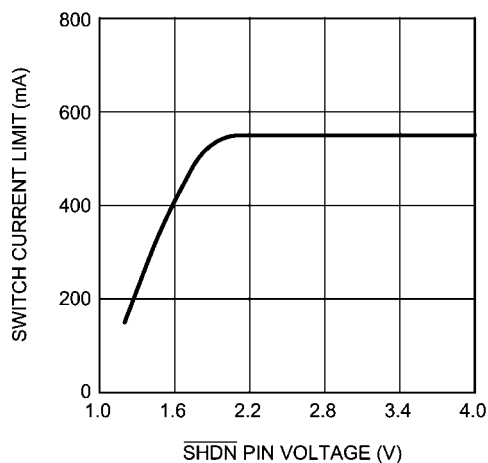


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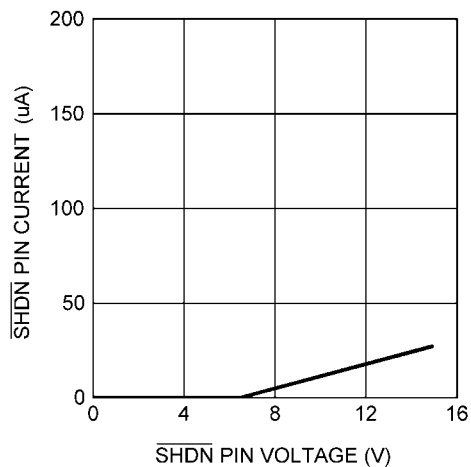
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**Switch Current Limit vs.  $\overline{SHDN}$  Pin Voltage**  
(Soft-start Implementation)



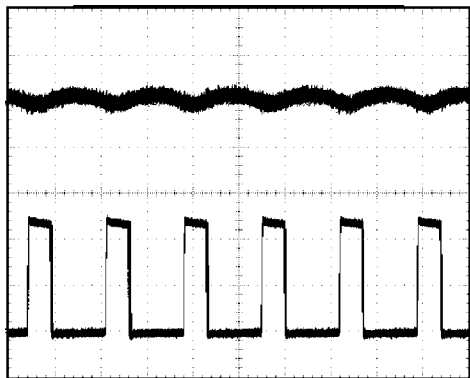
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**$\overline{SHDN}$  Pin Current vs.  $\overline{SHDN}$  Pin Voltage**



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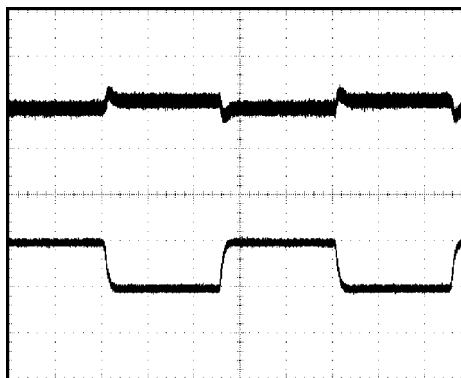
**Switching Node and Output Voltage Waveforms**



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$V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $I_{OUT} = 200\text{ mA}$   
 Top trace:  $V_{OUT}$ , 10 mV/div, AC Coupled  
 Bottom trace: SW, 5V/div, DC Coupled  
 T = 1  $\mu\text{s}/\text{div}$

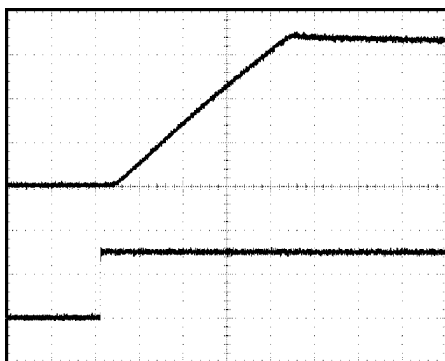
**Load Transient Waveforms**



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$V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $I_{OUT} = 300\text{ mA to } 200\text{ mA to } 300\text{ mA}$   
 Top trace:  $V_{OUT}$ , 20 mV/div, AC Coupled  
 Bottom trace:  $I_{OUT}$ , 100 mA/div, DC Coupled  
 T = 200  $\mu\text{s}/\text{div}$

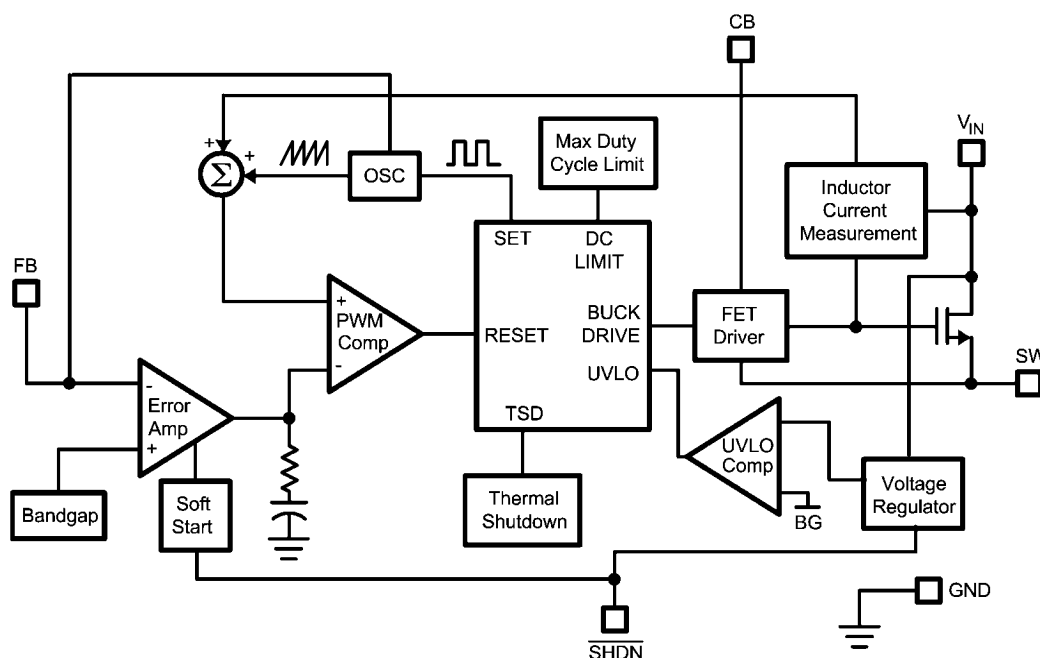
Start-Up Waveform



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 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $I_{OUT} = 50\text{ mA}$ Top trace:  $V_{OUT}$ , 1V/div, DC CoupledBottom trace:  $\overline{SHDN}$ , 2V/div, DC Coupled $T = 40\text{ }\mu\text{s/div}$

## Block Diagram



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## General Description

The LMR14203 is a PWM DC/DC buck (step-down) regulator. With a wide input range from 4.5V-42V, it is suitable for a wide range of applications such as power conditioning from unregulated sources. They feature a low  $R_{DS(on)}$  (0.9Ω typical) internal switch for maximum efficiency (85% typical). Operating frequency is fixed at 1.25 MHz allowing the use of small external components while still being able to have low output voltage ripple. Soft-start can be implemented using the shutdown pin with an external RC circuit allowing the user to tailor the soft-start time to a specific application.

The LMR14203 is optimized for up to 300 mA load current.

Additional features include: thermal shutdown,  $V_{IN}$  under-voltage lockout, and gate drive under-voltage lockout. The LMR14203 is available in a low profile TSOT-6L package.

## Application Information

### PROTECTION

The LMR14203 has dedicated protection circuitry running during normal operation to protect the IC. The thermal shutdown circuitry turns off the power device when the die temperature reaches excessive levels. The UVLO comparator protects the power device during supply power startup and shutdown to prevent operation at voltages less than the minimum input voltage. A gate drive (CB) under-voltage lockout is included to guarantee that there is enough gate drive voltage to drive the MOSFET before the device tries to start switching. The LMR14203 also features a shutdown mode decreasing the supply current to approximately 16 μA.

### CONTINUOUS CONDUCTION MODE

The LMR14203 contains a current-mode, PWM buck regulator. A buck regulator steps the input voltage down to a lower output voltage. In continuous conduction mode (when the in-

ductor current never reaches zero at steady state), the buck regulator operates in two cycles. The power switch is connected between  $V_{IN}$  and SW. In the first cycle of operation the transistor is closed and the diode is reverse biased. Energy is collected in the inductor and the load current is supplied by  $C_{OUT}$  and the rising current through the inductor. During the second cycle the transistor is open and the diode is forward biased due to the fact that the inductor current cannot instantaneously change direction. The energy stored in the inductor is transferred to the load and output capacitor. The ratio of these two cycles determines the output voltage. The output voltage is defined approximately as:  $D = V_{OUT}/V_{IN}$  and  $D' = (1-D)$  where D is the duty cycle of the switch. D and D' will be required for design calculations.

### DESIGN PROCEDURE

This section presents guidelines for selecting external components.

#### SETTING THE OUTPUT VOLTAGE

The output voltage is set using the feedback pin and a resistor divider connected to the output as shown on the front page schematic. The feedback pin voltage is 0.762V, so the ratio of the feedback resistors sets the output voltage according to the following equation:  $V_{OUT} = 0.765V(1 + (R1/R2))$ . Typically R2 will be given as 100Ω-10 kΩ for a starting value. To solve for R1 given R2 and  $V_{OUT}$  use  $R1 = R2((V_{OUT}/0.765V) - 1)$ .

#### INPUT CAPACITOR

A low ESR ceramic capacitor ( $C_{IN}$ ) is needed between the  $V_{IN}$  pin and GND pin. This capacitor prevents large voltage transients from appearing at the input. Use a 2.2 μF-10 μF value with X5R or X7R dielectric. Depending on construction, a ceramic capacitor's value can decrease up to 50% of its nominal value when rated voltage is applied. Consult with the capacitor manufacturer's data sheet for information on capacitor derating over voltage and temperature.



## INDUCTOR SELECTION

The most critical parameters for the inductor are the inductance, peak current, and the DC resistance. The inductance is related to the peak-to-peak inductor ripple current, the input and the output voltages.

$$L = \frac{(V_{IN} - V_{OUT})V_{OUT}}{V_{IN} \times I_{RIPPLE} \times f_{SW}}$$

A higher value of ripple current reduces inductance, but increases the conductance loss, core loss, and current stress for the inductor and switch devices. It also requires a bigger output capacitor for the same output voltage ripple requirement. A reasonable value is setting the ripple current to be 30% of the DC output current. Since the ripple current increases with the input voltage, the maximum input voltage is always used to determine the inductance. The DC resistance of the inductor is a key parameter for the efficiency. Lower DC resistance is available with a bigger winding area. A good tradeoff between the efficiency and the core size is letting the inductor copper loss equal 2% of the output power. See AN-1197 for more information on selecting inductors. A good starting point for most applications is a 10  $\mu$ H to 22  $\mu$ H with a 0.7A or greater current rating for the LMR14203. Using such a rating will enable the LMR14203 to current limit without saturating the inductor. This is preferable to the device going into thermal shutdown mode and the possibility of damaging the inductor if the output is shorted to ground or other longterm overload.

## OUTPUT CAPACITOR

The selection of  $C_{OUT}$  is driven by the maximum allowable output voltage ripple. The output ripple in the constant frequency, PWM mode is approximated by:  $V_{RIPPLE} = I_{RIPPLE} (ESR + (1/(8f_{SW}C_{OUT})))$ . The ESR term usually plays the dominant role in determining the voltage ripple. Low ESR ceramic capacitors are recommended. Capacitors in the range of 22  $\mu$ F-100  $\mu$ F are a good starting point with an ESR of 0.1 $\Omega$  or less.

## BOOTSTRAP CAPACITOR

A 0.15  $\mu$ F ceramic capacitor or larger is recommended for the bootstrap capacitor ( $C_{BOOT}$ ). For applications where the input voltage is less than twice the output voltage a larger capacitor is recommended, generally 0.15  $\mu$ F to 1  $\mu$ F to ensure plenty of gate drive for the internal switches and a consistently low  $R_{DS(on)}$ .

## SOFT-START COMPONENTS

The LMR14203 has circuitry that is used in conjunction with the SHDN pin to limit the inrush current on start-up of the DC/DC switching regulator. The SHDN pin in conjunction with a

RC filter is used to tailor the soft-start for a specific application. When a voltage applied to the SHDN pin is between 0V and up to 2.3V it will cause the cycle by cycle current limit in the power stage to be modulated for minimum current limit at 0V up to the rated current limit at 2.3V. Thus controlling the output rise time and inrush current at startup. The resistor value should be selected so the current sourced into the SHDN pin will be greater than the leakage current of the SHDN pin (1.5  $\mu$ A) when the voltage at SHDN is equal or greater than 2.3V.

## SHUTDOWN OPERATION

The SHDN pin of the LMR14203 is designed so that it may be controlled using 2.3V or higher logic signals. If the shutdown function is not to be used the SHDN pin may be tied to  $V_{IN}$ . The maximum voltage to the SHDN pin should not exceed 42V. If the use of a higher voltage is desired due to system or other constraints it may be used, however a 100 k $\Omega$  or larger resistor is recommended between the applied voltage and the SHDN pin to protect the device.

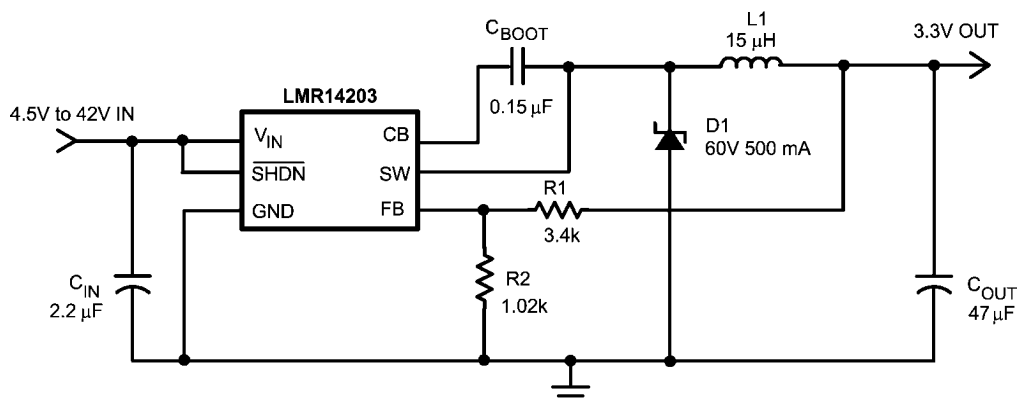
## SCHOTTKY DIODE

The breakdown voltage rating of the diode (D1) is preferred to be 25% higher than the maximum input voltage. The current rating for the diode should be equal to the maximum output current for best reliability in most applications. In cases where the input voltage is much greater than the output voltage the average diode current is lower. In this case it is possible to use a diode with a lower average current rating, approximately (1-D) $I_{OUT}$ , however the peak current rating should be higher than the maximum load current. A 0.5A to 1A rated diode is a good starting point.

## LAYOUT CONSIDERATIONS

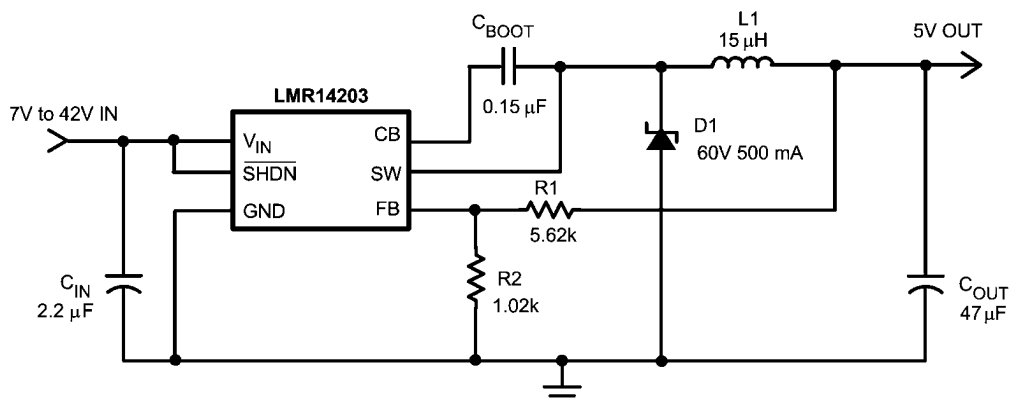
To reduce problems with conducted noise pick up, the ground side of the feedback network should be connected directly to the GND pin with its own connection. The feedback network, resistors R1 and R2, should be kept close to the FB pin, and away from the inductor to minimize coupling noise into the feedback pin. The input bypass capacitor  $C_{IN}$  must be placed close to the  $V_{IN}$  pin. This will reduce copper trace resistance which effects input voltage ripple of the IC. The inductor L1 should be placed close to the SW pin to reduce magnetic and electrostatic noise. The output capacitor,  $C_{OUT}$  should be placed close to the junction of L1 and the diode D1. The L1, D1, and  $C_{OUT}$  trace should be as short as possible to reduce conducted and radiated noise and increase overall efficiency. The ground connection for the diode,  $C_{IN}$ , and  $C_{OUT}$  should be as small as possible and tied to the system ground plane in only one spot (preferably at the  $C_{OUT}$  ground point) to minimize conducted noise in the system ground plane. For more detail on switching power supply layout considerations see Application Note AN-1149: *Layout Guidelines for Switching Power Supplies*.

## Typical Applications



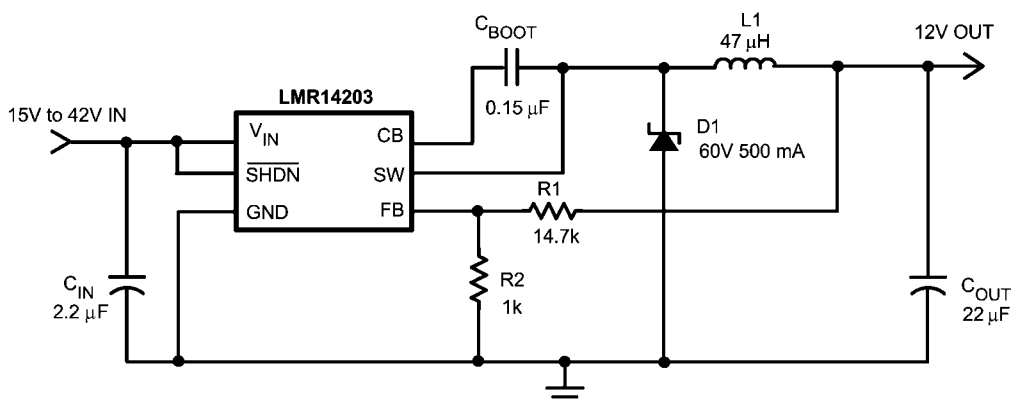
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FIGURE 1. Application Circuit, 3.3V Output



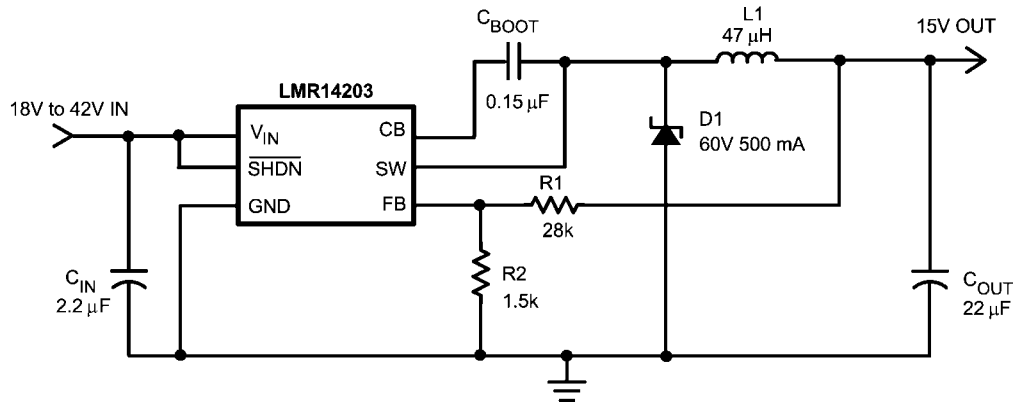
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FIGURE 2. Application Circuit, 5V Output



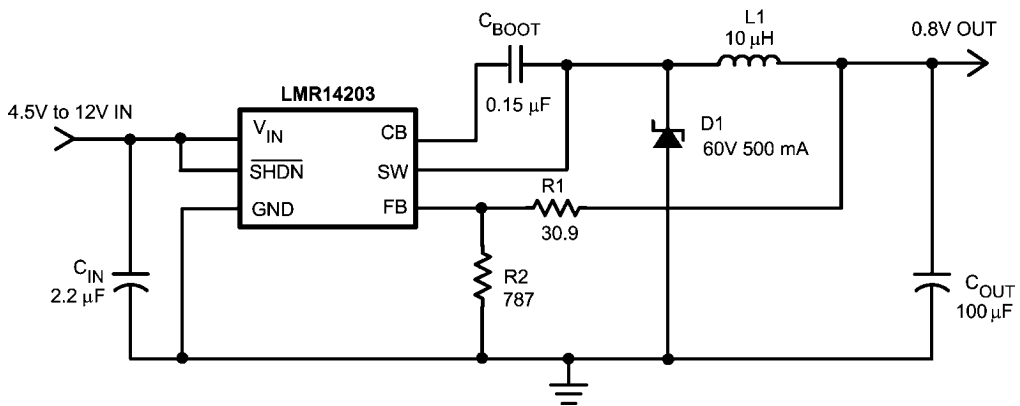
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FIGURE 3. Application Circuit, 12V Output



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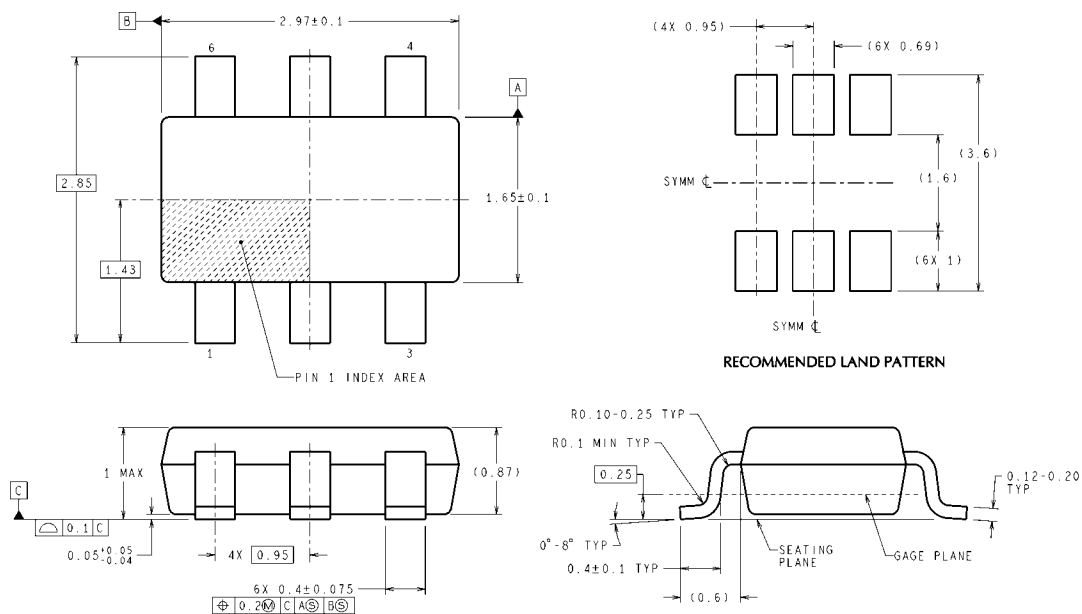
FIGURE 4. Application Circuit, 15V Output



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FIGURE 5. Application Circuit, 0.8V Output

# Physical Dimensions inches (millimeters) unless otherwise noted



DIMENSIONS ARE IN MILLIMETERS

MK06A (Rev E)

**TSOT 6 Pin Package (MK)**  
**For Ordering, Refer to Ordering Information Table**  
**NS Package Number MK06A**

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DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
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Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Mobile Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Transportation and Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

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